**IN THE CLAIMS:**

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~strikethrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please CANCEL claim 3 without prejudice or disclaimer and AMEND claims 1, 4, 11, and 14:

1. (CURRENTLY AMENDED) A semiconductor wafer transfer apparatus comprising:

a wafer supporting block to support a semiconductor wafer;

a casing formed along a moving path of the wafer supporting block and having a guide slot through which a part of the wafer supporting block passes;

a driving part which is accommodated in the casing and moves the wafer supporting block;

a connection part which connects the driving part with the wafer supporting block; ~~and~~

a shield part which shields the driving part from the guide ~~slot.~~ slot; and

a first auxiliary shield part which is provided inside the casing and shields the connection part from the guide slot.

2. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 1, further comprising a guide unit which includes:

a guide member provided inside the casing and having a first end combined to the connection part and a second end combined to the wafer supporting block; and

a guide rail which is attached to a floor of the casing and guides the guide member, wherein the shield part is provided between the guide unit and the driving part.

3. (CANCELLED)

4. (CURRENTLY AMENDED) The semiconductor wafer transfer apparatus according to claim ~~3,~~ 2, further comprising a second auxiliary shield part which is provided in a lower part of the guide slot and shields the guide unit from the guide slot.

5. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 1, wherein the driving part includes:

a belt which is connected to the connection part and moves the connection part;

pulleys which engage with the belt; and

a driving motor which drives at least one of the pulleys.

6. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 5, wherein:

the belt is a timing belt, and

the pulleys engage with the timing belt.

7. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 1, wherein the shield part has a plate like shape.

8. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 1, wherein the shield part shields the driving part so as to prevent dust and particles from leaking out through the guide slot.

9. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 2, wherein the guide unit further includes one or more ball bearings which are provided between the guide member and the guide rail.

10. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 4, wherein:

the shield part primarily prevents dust and particles from leaking out through the guide slot,

the first auxiliary shield part secondarily prevents the dust and particles from leaking out through the guide slot, and

the second auxiliary shield part further prevents the dust and particles that have passed through the first auxiliary shield part from leaking out through the guide slot.

11. (CURRENTLY AMENDED) A semiconductor wafer transfer apparatus comprising:

a wafer supporting block to support a semiconductor wafer;

a casing formed along a moving path of the wafer supporting block and having a guide slot through which a part of the wafer supporting block passes;

a driving part which is accommodated in the casing and moves the wafer supporting block;

a connection part which connects the driving part with the wafer supporting block; and

a shield part which partitions the casing so as to limit communication between the driving part and the guide slot, wherein the shield part includes a first shield part, a second shield part, and a third shield part, and wherein the second shield part is provided between the connection part and the guide slot .

12. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 11, wherein the shield part shields the driving part so as to prevent dust and particles from leaking out through the guide slot.

13. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 11, further comprising a guide unit which includes:

a guide member provided inside the casing and having a first end combined to the connection part and a second end combined to the wafer supporting block; and

a guide rail which is attached to a floor of the casing of the casing and guides the guide member.

14. (CURRENTLY AMENDED) The semiconductor wafer transfer apparatus according to claim 13, wherein: ~~the shield part includes:~~

~~a~~ the first shield part ~~which~~ is provided between the guide unit and the driving part; and

~~a second shield part which is provided between the connection part and the guide slot; and~~

~~a~~ the third shield part ~~which~~ is provided between the guide unit and the guide slot.

15. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 13, wherein the guide unit further includes one or more ball bearings which are provided between the guide member and the guide rail.

16. (ORIGINAL) The semiconductor wafer transfer apparatus according to claim 11, wherein the shield part prevents an outflow of dust and particles from the casing to the outside of

the casing.